

**Amendments to the Specification:**

Please insert the following between sections [0010] and [0015] on page 4 of the specification:

--[0011] Fig. 19 shows an embodiment in which an optoelectronic device is to be flipped vertically by solder surface tension forces.

[0012] Fig. 20 shows the device of Fig. 19 after the optoelectronic device is flipped vertically.--